



Material Content Data Sheet



Sales Product Name		BGA 728L7 E6327		Issued		30. January 2015		
MA#		MA000505226						
Package		PG-TSLP-7-1		Weight*		1.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.147	9.12	9.12	91165	91165
leadframe	non noble metal	nickel	7440-02-0	0.329	20.34	20.34	203415	203415
wire	noble metal	gold	7440-57-5	0.043	2.69	2.69	26853	26853
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		294	
	organic material	carbon black	1333-86-4	0.010	0.59		5886	
	plastics	epoxy resin	-	0.128	7.95		79455	
encapsulation	inorganic material	silicondioxide	60676-86-0	0.813	50.27	58.84	502921	588556
	leadfinish	noble metal	gold	7440-57-5	0.032	1.96	1.96	19573
plating	noble metal	gold	7440-57-5	0.032	1.96	1.96	19573	19573
glue	plastics	epoxy resin	-	0.016	1.02		10173	
	noble metal	silver	7440-22-4	0.066	4.07	5.09	40692	50865
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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